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Specification

MCCOG240128A6W-FPTLW

Contents

1. Revision History

DATE	VERSION	REVISED PAGE NO.	Note
2011/06/13	1		First issue

2. General Specification

The Features of the Module is description as follow:

- Module dimension: 98.7x 67.7 x 9.5 (max.) mm^3
- View area: 92.0 x 53.0 mm^2
- Active area: 83.975 x 44.775mm^2
- Number of Dots: 240 x 128
- Dot size: 0.325 x 0.325 mm^2
- Dot pitch: 0.35 x 0.35 mm^2
- LCD type: FSTN Positive Transflective,
- Duty: 1/128
- View direction: 6 o'clock
- Backlight Type: LED White

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Midas LCD Part Number System

MC	COG	132033	A	*	6	W	*	*	-	S	N	T	L	W	*	*
1	2	3	4	5	6	7	8	9	-	10	11	12	13	14	15	16

1 = **MC:** Midas Components

2 = **Blank:** COB (chip on board) **COG**: chip on glass

3 = **No of dots** (e.g. 240064 = 240 x 64 dots) (e.g. 21605 = 2 x 16 5mm C.H.)

4 = **Series**

5 = **Series Variant:** A to Z – see addendum

6 = **3:** 3 o'clock **6:** 6 o'clock **9**: 9 o'clock **12**: 12 o'clock

7 = **S**: Normal (0 to + 50 deg C) **W:** Wide temp. (-20 to + 70 deg C) **X:** Extended temp (-30 + 80 Deg C)

8 = **Character Set**

Blank: Standard (English/Japanese)
C: Chinese Simplified (Graphic Displays only)
CB: Chinese Big 5 (Graphic Displays only)
H: Hebrew
K: European (std) (English/German/French/Greek)
L: English/Japanese (special)
M: European (English/Scandinavian)
R: Cyrillic
W: European (English/Greek)
U: European (English/Scandinavian/Icelandic)

9 = **Bezel Height** (where applicable / available)

	Top of Bezel to Top of PCB	Common (via pins 1 and 2)	Array or Edge Lit
Blank	9.5mm / not applicable	Common	Array
2	8.9 mm	Common	Array
3	7.8 mm	Separate	Array
4	7.8 mm	Common	Array
5	9.5 mm	Separate	Array
6	7 mm	Common	Array
7	7 mm	Separate	Array
8	6.4 mm	Common	Edge
9	6.4 mm	Separate	Edge
A	5.5 mm	Common	Edge
B	5.5 mm	Separate	Edge
D	6.0mm	Separate	Edge
E	5.0mm	Separate	Edge
F	4.7mm	Common	Edge
G	3.7mm	Separate	EL

10 = **T:** TN **S**: STN **B:** STN Blue **G:** STN Grey **F:** FSTN **F2:** FFSTN

11 = **P:** Positive **N**: Negative

12 = **R:** Reflective **M**: Transmissive **T:** Transflective

13 = **Backlight: Blank:** Reflective **L:** LED

14 = **Backlight Colour: Y:** Yellow-Green **W:** White **B:** Blue **R:** Red **A:** Amber **O:** Orange **G:** Green **RGB:** R.G.B.

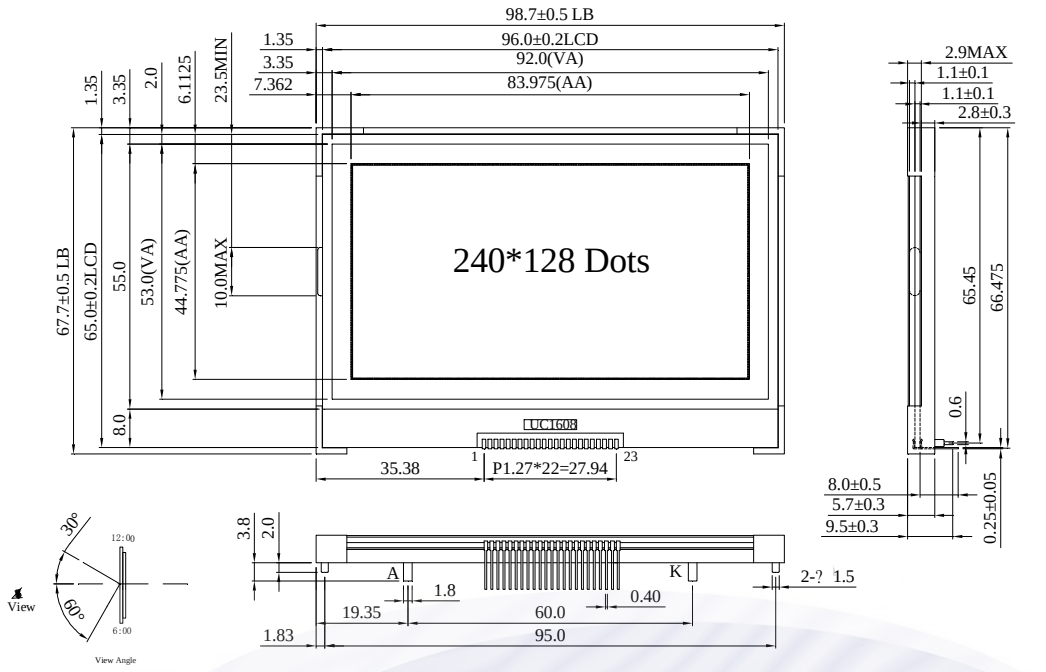
15 = **Driver Chip: Blank:** Standard **I:** I²C **T:** Toshiba T6963C **A:** Avant SAP1024B **R:** Raio RA8835

16 = **Voltage Variant**: e.g. **3** = 3v

4. Interface Pin Function

Pin No.	Symbol	Type	Description
1	VB1-	PWR	LCD Bias Voltages. These voltages are always generated internally. Connect capacitors of CB value between VBX+ toVBX+.
2	VB1+		
3	VB0-		
4	VB0+		
5	V_{LCD}	PWR	Main LCD power supply.
6	V_{BIAS}		Reference voltages to generate the actual seg driving voltages
7	V_{SS}	PWR	Ground
8	V_{DD}	PWR	Supply Voltage for logic
9	D7	I/O	Bi-directional bus for both serial and parallel host interfaces. Connect unused pins to VSS in serial modes. When PS1=”L”, D0: SCK (serial clock), D2: SDI (input data), D4: SDO (output data), D1, D3, D5~7: High impedance, connect to VSS. When PS1=”H”, D[7:0] is under the control of WR[1:0] and CS[1:0]
10	D6		
11	D5		
12	D4		
13	D3		
14	D2		
15	D1		
16	D0		
17	WR1	I	WR[1:0] controls the read/write operation of the host interface. In parallel mode, WR[1:0] meaning depends on whether the interface is in the 6800 mode or the 8080 mode. In serial interface modes, these two pins are not used. Connect to VSS.
18	WR0		
19	CD	I	Select Control data or Display data for read/write operation. When in serial 9-bit mode, this pin is not used, connect to VSS. ”L”: Control data ”H”: Display data
20	RST	I	When RST=”L”, all control registers are reinitialized by their default states and/or by their pin configurations if applicable. When RST is not used, connect the pin to VDD1.
21	CS	I	Chip Select. Chip selected when CE=”H”.
22	BM0	I	Bus modes: Serial modes: “LL”: SPI 2-bit serial mode. Parallel modes: “HL”: 8080 “HH”: 6800
23	BM1		

5. Outline Dimension & Block Diagram



PIN NO.	SYMBOL
1	VB1-
2	VB1+
3	VB0-
4	VB0+
5	VLCD
6	VBIAS
7	VSS
8	VDD
9	D7
10	D6
11	D5
12	D4
13	D3
14	D2
15	D1
16	D0
17	WR1
18	WR0
19	CD
20	RST
21	CS
22	BM0
23	BM1

The non-specified tolerance of dimension is ±0.2mm.

6. Display Command

The following is a list of host commands support by UC1608

C/D: 0: Control, 1: Data

W/R: 0: Write Cycle, 1: Read Cycle

Useful Data bits

– Don't Care

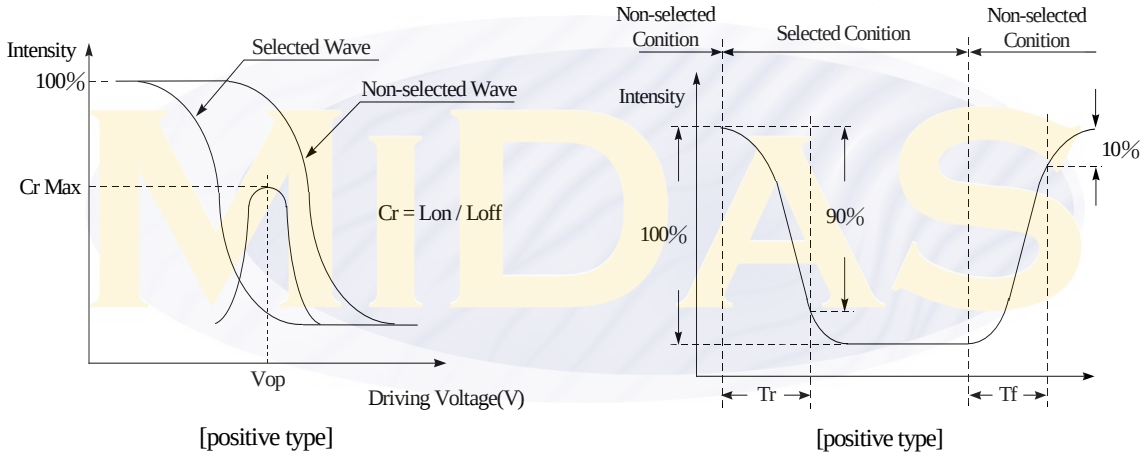
Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Action
Write Data Byte	1	0	#	#	#	#	#	#	#	#	Write 1 byte @ PA/CA
Read Data Byte	1	1	#	#	#	#	#	#	#	#	Read 1 byte @ PA/CA
Get Status	0	1	BZ	MX	DE	RS	0	0	0	0	Get Status Summary
Set Column Address LSB	0	0	0	0	0	0	#	#	#	#	Set CA[3:0]=D[3:0]
Set Column Address MSB	0	0	0	0	0	1	#	#	#	#	Set CA[7:4] =D[3:0]
Set Mux rate & Gain Parameter.[1)]	0	0	0	0	1	0	0	#	#	#	Set MR=D[2] Set GN[1:0]=D[1:0]
Set Mux rate & Temperature Compensation.[2)]	0	0	0	0	1	0	0	#	#	#	Set MR=D[2] Set TC[1:0]=D[1:0]
Set Power Control	0	0	0	0	1	0	1	#	#	#	Set PC[2:0]=D[2:0]
Set Adv. Program Control (double byte command)	0 0	0 0	0 #	0 #	1 #	1 #	0 #	0 #	R #	 #	Set APC[R][7:0]=D[7:0], where R = 00, or 01
Set Start Line	0	0	0	1	#	#	#	#	#	#	Set SL[5:0]=D[5:0]
Set V_{REF} potential meter (double-byte command)[1)]	0 0	0 0	1 #	0 #	0 #	0 #	0 #	0 #	0 #	1 #	Set PM[5:0]=D[5:0] Set TC[1:0]=D[7:6]
Set V_{REF} potential meter (double-byte command)[2)]	0 0	0 0	1 #	0 #	0 #	0 #	0 #	0 #	0 #	1 #	Set PM[5:0]=D[5:0] Set GN[1:0]=D[7:6]
Set RAM Address Control	0	0	1	0	0	0	1	#	#	#	Set AC[2:0]=D[2:0]
Set Serial Bus Control	0	0	1	0	0	1	0	0	#	#	Set BC[1:0]=D[1:0]
Set Column Mirroring	0	0	1	0	1	0	0	0	0	#	Set LC[2]=D0
Set All-Pixel-ON	0	0	1	0	1	0	0	1	0	#	Set DC[1]=D0
Set Inverse Display	0	0	1	0	1	0	0	1	1	#	Set DC[0]=D0
Set Display ON/OFF	0	0	1	0	1	0	1	#	#	#	Set DC[4:2]=D[2:0]
Set Page Address	0	0	1	0	1	1	#	#	#	#	Set PA[3:0]=D[3:0]
Set LCD to RAM Mapping	0	0	1	1	0	0	#	#	#	#	Set LC[3:0]=D[3:0]
System Reset	0	0	1	1	1	0	0	0	1	0	System Reset sequence
NOP	0	0	1	1	1	0	0	0	1	1	No operation
Set LCD Bias Ratio	0	0	1	1	1	0	1	0	#	#	Set BR[1:0]= D[1:0]
Reset Cursor Update Mode	0	0	1	1	1	0	1	1	1	0	Set AC[3]=0, CA=CR;
Set Cursor Update Mode	0	0	1	1	1	0	1	1	1	1	Set AC[3]=1, CR=CA;
Set Test Control (double byte command)	0 0	0 0	1 #	1 #	1 #	0 #	0 #	1 #	TT #	 #	For testing only. Do not use.

7. Optical Characteristics

Ta=25^{0}C

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	(V)θ	CR≧2	30	—	60	deg
	(H)φ	CR≧2	-45	—	45	deg
Contrast Ratio	CR	—	—	5	—	—
Response Time	T rise	—	—	200	300	ms
	T fall	—	—	250	350	ms

Definition of Operation Voltage (Vop) **Definition of Response Time (Tr , Tf)**

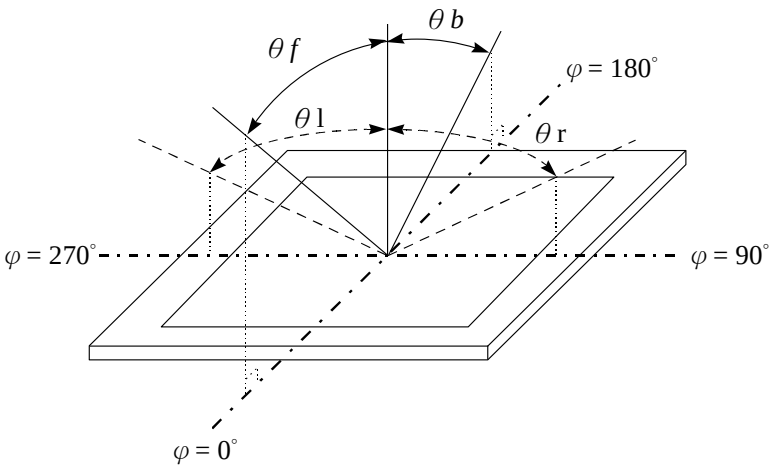


Conditions :

Operating Voltage : Vop Viewing Angle(θ ， φ) : 0˚， 0˚

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR≧2)



8. Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	℃
Storage Temperature	T_{ST}	-30	—	+80	℃
Input Voltage	V_{IN}/V_{OUT}	-0.3	—	V_{DD}+0.3	V
Supply Voltage For Logic	V_{DD}-V_{SS}	-0.3		4.0	V
LCD Driver Supply Voltage	V_{LCD}	-0.3		+18.0	V

9. Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	V_{DD}-V_{SS}	—	2.7	3.0	3.3	V
Supply Voltage For LCM	V_{DD}-V_5	Ta=-20℃	—	—	—	V
		Ta=25℃	—	15.5	—	V
		Ta=70℃	—	—	—	V
Supply Current(No include LED Backlight)	I_{DD}	V_{DD}=3.0V		1.1		mA

10. Backlight Information

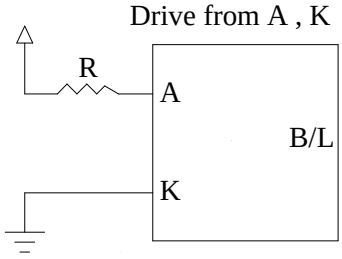
Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	86.4	96	1200	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	
Reverse Voltage	VR	—	—	5	V	—
Luminous Intensity (Without LCD)	IV	480	600	—	CD/M2	ILED=96mA
Wave Length	X	0.26	0.28	0.3		ILED=96mA
	Y	0.28	0.3	0.32		
LED Life Time (For Reference only)	—	—	50K	—	Hr.	ILED≦96mA 25℃,50-60%RH, (Note 1)
Color	White					

Note: The LED of B/L is drive by current only；driving voltage is only for reference
To make driving current in safety area (waste current between minimum and maximum).

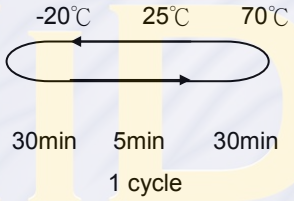
Note 1:50K hours is only an estimate for reference.

LED B\L Drive Method
Drive from A , K



11. Reliability

Content of Reliability Test (wide temperature, -20℃~70℃)

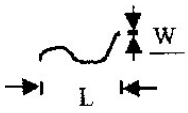
Environmental Test			
Test Item	**Content of Test**	**Condition**	**Note**
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30℃ 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs	-
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60℃,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  	-20℃/70℃ 10 cycles	-
Vibration test	Endurance test applying the vibration during transportation and using.	fixed amplitude: 15mm Vibration. Frequency: 10~55Hz. One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	——

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

12. Inspection specification

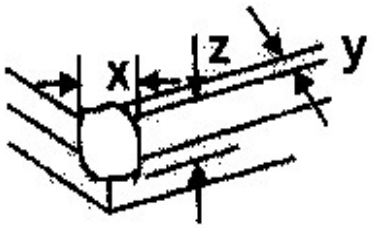
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>01</td><td>Electrical Testing</td><td>1.1 Missing vertical, horizontal segment, segment contrast defect.
1.2 Missing character, dot or icon.
1.3 Display malfunction.
1.4 No function or no display.
1.5 Current consumption exceeds product specifications.
1.6 LCD viewing angle defect.
1.7 Mixed product types.
1.8 Contrast defect.</td><td>0.65</td></tr>
<tr><td>02</td><td>Black or white spots on LCD (display only)</td><td>2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present.
2.2 Densely spaced: No more than two spots or lines within 3mm</td><td>2.5</td></tr>
<tr><td rowspan="2">03</td><td rowspan="2">LCD black spots, white spots, contamination (non-display)</td><td>3.1 Round type : As following drawing
Φ=(x + y) / 2</td><td>2.5</td></tr>
<tr><td>3.2 Line type : (As following drawing)
 

<table>
<tr><th></th><th>Width</th><th>Acceptable Q TY</th></tr>
<tr><td>---</td><td>W≦0.02</td><td>Accept no dense</td></tr>
<tr><td>L≦3.0</td><td>0.02＜W≦0.03</td><td rowspan="2">2</td></tr>
<tr><td>L≦2.5</td><td>0.03＜W≦0.05</td></tr>
<tr><td>---</td><td>0.05＜W</td><td>As round type</td></tr>
</table></td><td>2.5</td></tr>
<tr><td>04</td><td>Polarizer bubbles</td><td>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.
<table>
<tr><th>Size Φ</th><th>Acceptable Q TY</th></tr>
<tr><td>Φ≦0.20</td><td>Accept no dense</td></tr>
<tr><td>0.20＜Φ≦0.50</td><td>3</td></tr>
<tr><td>0.50＜Φ≦1.00</td><td>2</td></tr>
<tr><td>1.00＜Φ</td><td>0</td></tr>
<tr><td>Total Q TY</td><td>3</td></tr>
</table></td><td>2.5</td></tr>
</table>

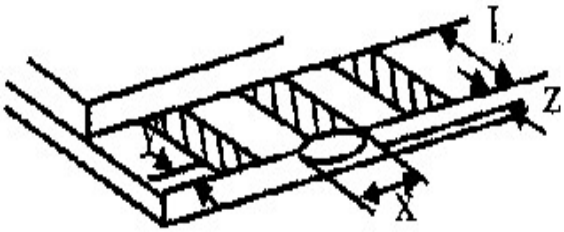
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>05</td><td>Scratches</td><td>Follow NO.3 LCD black spots, white spots, contamination</td><td></td></tr>
<tr><td>06</td><td>Chipped glass</td><td>
Symbols Define:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length:

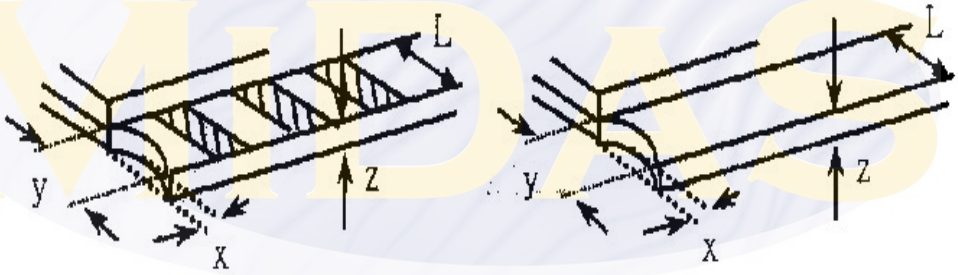
6.1 General glass chip :
6.1.1 Chip on panel surface and crack between panels:

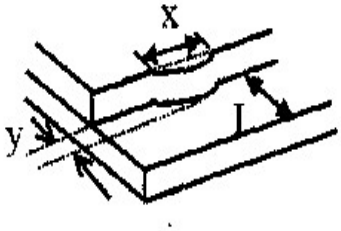
<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>
⊙If there are 2 or more chips, x is total length of each chip.

6.1.2 Corner crack:


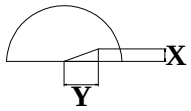
<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>
⊙If there are 2 or more chips, x is the total length of each chip.
</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>06</td><td>Glass crack</td><td>
Symbols :
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
6.2 Protrusion over terminal :
6.2.1 Chip on electrode pad :


<table>
<tr><th>y: Chip width</th><th>x: Chip length</th><th>z: Chip thickness</th></tr>
<tr><td>y≦0.5mm</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>
6.2.2 Non-conductive portion:


<table>
<tr><th>y: Chip width</th><th>x: Chip length</th><th>z: Chip thickness</th></tr>
<tr><td>y≦ L</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>
⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
⊙If the product will be heat sealed by the customer, the alignment mark not be damaged.
6.2.3 Substrate protuberance and internal crack.


<table>
<tr><th>y: width</th><th>x: length</th></tr>
<tr><td>y≦1/3L</td><td>x ≦ a</td></tr>
</table>
</td><td>2.5</td></tr>
</table>

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  **X * Y<=2mm^2**	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

13. Precautions in use of LCD Modules

1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
2. Don’t make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
3. Don’t disassemble the LCM.
4. Don’t operate it above the absolute maximum rating.
5. Don’t drop, bend or twist LCM.
6. Soldering: only to the I/O terminals.
7. Storage: please storage in anti-static electricity container and clean environment.
8. Midas have the right to change the passive components
   (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
9. Midas have the right to change the PCB Rev.

14. Material List of Components for RoHs

1. MIDAS Components Ltd. hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

   Exhibit A：The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2. Process for RoHS requirement：
   (1) Use the Sn/Ag/Cu soldering surface；the surface of Pb-free solder is rougher than we used before.
   (2) Heat-resistance temp.：
   Reflow：250℃, 30 seconds Max.；
   Connector soldering wave or hand soldering：320℃, 10 seconds max.
   (3) Temp. curve of reflow, max. Temp.：235±5℃；
   Recommended customer's soldering temp. of connector：280℃, 3 seconds.

15. Recommendable storage

1. Place the panel or module in the temperature 25°C±5℃ and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module